



Ku Ping Enterprise Co. Ltd

Pure Core Solder Wire (水溶性樹脂心焊錫絲)

Because of current concern with environmentally sound manufacturing processes, KuPing has used the most advanced technology to produce a solder with high-condensation rosin. When used in water-cleaning machines, rosin residue is eliminated quickly and efficiently.

Features

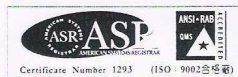
- 1 . High activation level; all forms of soldering can be finished Quickly
2. No halogens; will not corrode, splash or give off odors
3. Rosin residue dissolves quickly in water
4. Solder spots are shiny and clean

Classification & package

Composition %	Melting point°C	Specific gr	Diameter (mm)	Package
Sn/Pb 63/37	183	8.4	0.3 : 2.0	0.1KG ↓ 10KG
Sn/Pb 60/40	191			



臺灣固品企業有限公司
Ku Ping Enterprise Co., Ltd.



試驗報告表
TEST REPORT

試驗結果：
Result

SN-02 SN-Sn/Pb 63/37 6604/95 06/27/13 14:22

Sample-No 60/40 Solder Wire

	Pb	Sb	As	Bi	Cd	In	Ag
1	40.01	0.0137	.00616	.00385	.00100	.00280	.00274
2	40.09	0.0139	.00636	.00383	.00098	.00277	.00269

	Cu	Al	Fe	Ni	Zn	Sn
1	.00743	.00033	.00270	.00083	.00118	59.94
2	.00726	.00033	.00272	.00084	.00118	59.86

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Sample-No 60/40 Solder Wire

Average of 2 sparks

	Pb	Sb	As	Bi	Cd	In	Ag
X	40.05	0.0138	.00626	.00384	<.00100	.00278	.00272

	Cu	Al	Fe	Ni	Zn	Sn
X	.00734	<.00100	.00271	<.00100	.00118	59.90

試驗品名：

Name of Article SOLDER

試驗日期：

Date 表圖右上角

試驗依據：
Method SPARK-ATOMIC ENISSION
SPECTROMETER

試驗者：

Analyst

試驗數量：

Piece 1 PCS

委託者：

Applicant

試驗內容：
Content PB鉛 SB銻 AS銻 BI鉍 CD鎘 IN銲 AG銀 CU銅 AL鋁
FE鐵 NI鎳 ZN鋅 SN錫

備註：考慮換錫之標準，由各家自行定訂各雜質比之含量值，當雜質比超過所設值之上限，就應更換新錫。

Remark
1.為第一次化驗。
2.為第二次化驗。底下為平均值。



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Rosin-Core Solder Wire

SOLID FLUX CONTENT WT %	2% ~ 2.2%
固 體 助 錒 劑 含 量	
CHLORIDES CONTENT WT %	0.3% 0.4%
鹵 化 物 含 量	
CONDUCTIVITY Ω m	OVER 500 Ω m
水 溶 液 比 電 阻	
SPREADING %	OVER 90%
擴 散 率	
FLUX P H	P H 5.5
助 錒 劑 P H 值	
FLUX INSULATION RESISTANT	1×10^{10} OVER
助 錒 劑 絕 緣 阻 抗	
FLUX MELTING POINT	95 °c
助 錒 劑 軟 化 點	
CORROSION TEST	PASS
腐 蝕 試 驗	
DRYNESS	PASS
乾 燥 度	